Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-8. (Canceled)

9. (Currently Amended) A method of manufacturing a bump structure, comprising:

forming a liquid-repelling part with a liquid-repelling characteristic for droplets and a liquid-attracting part that is more wettable than the liquid-repelling part for the droplets on an upper surface of an insulating layer, the droplets including a precursor of UV-hardening resin;

discharging the droplets onto the liquid-attracting part to form a protruding part precursor;

hardening the protruding part precursor by applying UV rays to form a protruding part; ~~and~~

forming the protruding part directly on the insulating layer; and

forming a conductive layer so as to cover the protruding part,

discharging the droplets comprising discharging the droplets directly on the insulating layer without a conductor between the droplets and the insulating layer.

10-13. (Canceled)

14. (Original) The method of manufacturing a bump structure according to Claim 9, before the protruding part precursor is formed, a liquid repelling treatment being carried out on a region adjacent to a region in which the protruding part precursor is formed.

15. (Original) The method of manufacturing a bump structure according to Claim 9, the droplets being discharged using an ink jet method.

16-21. (Canceled)

22. (Previously Presented) The method of manufacturing a bump structure according to claim 9, forming the conductive layer comprising sandwiching the protruding part between the conductive layer and the insulating layer on which the droplets are discharged.

23. (New) The method of manufacturing a bump structure according to claim 9, forming a liquid-repelling part including using a plasma treatment.